onsemi

QFN16 3x3, 0.5P
CASE 485DA
ISSUE A

DATE 22 SEP 2015

SCALE 2:1

PIN ONE REFERENCE

2X ⌒ 0.10 C

2X ⌒ 0.10 C

TOP VIEW

// 0.05 C

⌒ 0.05 C
NOTE 4

DETAIL B

A

A3

A1

SIDE VIEW

SEATING PLANE C

DETAIL A
ALTERNATE CONSTRUCTIONS

EXPOSED Cu — A3 — **MOLD CMPD** — A3

A1

DETAIL B
ALTERNATE CONSTRUCTIONS
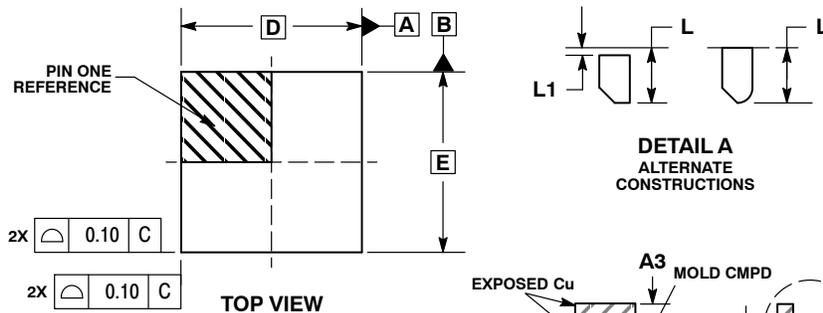
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	3.00 BSC	
D2	1.55	1.75
E	3.00 BSC	
E2	1.55	1.75
e	0.50 BSC	
K	0.275 REF	
L	0.30	0.50
L1	0.00	0.15
L2	0.09 REF	

DETAIL A

⊕ 0.10 C A B

⊕ 0.10 C A B

D2

16X L

8X L2

E2

16X b

⊕ 0.10 C A B
  0.05 C   NOTE 3

K

e

e/2

BOTTOM VIEW
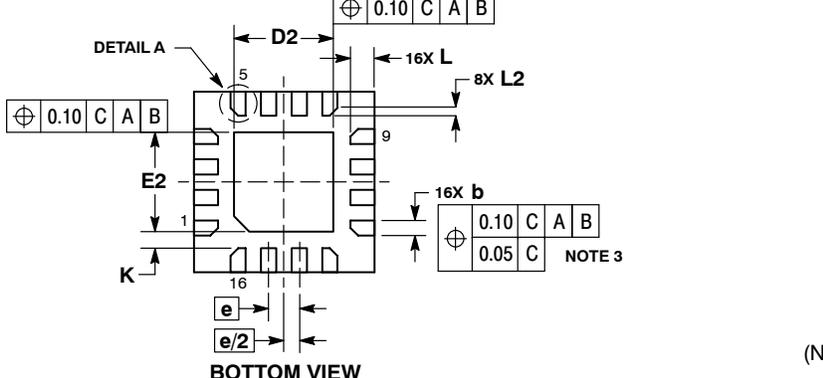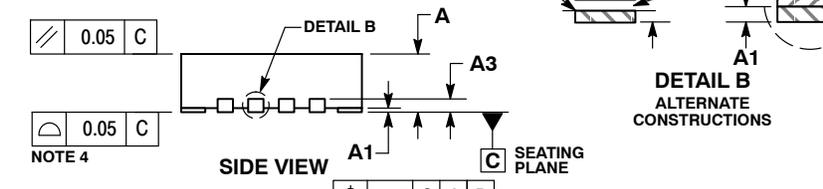
GENERIC MARKING DIAGRAM*

```
○ XXXXX
  XXXXX
  ALYW▪
     ▪
```
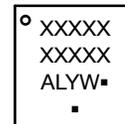
XXXXX = Specific Device Code
A   = Assembly Location
L   = Wafer Lot
Y   = Year
W   = Work Week
▪   = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot " ▪ ", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*

PACKAGE OUTLINE

3.30

1.78

16X 0.61

1.78   3.30

16X 0.30

0.50 PITCH

DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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